

# EE 330

## Section 5

### Homework 4

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September 19, 2019

This is just algebra busy work.  
There is little learning being done here.

1) Area of wafer =  $\pi(300/2)^2 = 70685.8mm^2$   
 # Chips/Wafer:  $70685.8/50 = 1413 \text{ chips}$   
 Hours/Year:  $365 \text{ days/yr} * 24 \text{ hrs/day} = 8760hrs$

248 nm Machine:	193 nm Machine:
Wafers/Year: 80 <i>wafers/hr</i> *	Wafers/Year: 20 <i>wafers/hr</i> *
$8760 \text{ hr/yr} = 700,800 \text{ wafers/yr}$	$8760 \text{ hr/yr} = 175,200 \text{ wafers/yr}$

Cost/Wafer: \$10M/700,800 =	Cost/Wafer: \$40M/175,200 =
\$14.27	\$228.31

Cost/Chip:  $\$14.27/1413 = \$0.01$       Cost/Chip:  $\$228.31/1413 = \$0.162$

Difference =  $\$0.162 - \$0.01 = \$0.152$

2) Dielectrics:  $SiO_2 = 3.9, HfO_2 = 25$ . Thickness must be proportional to dielectric, therefore  $t_{HfO_2} = 25/3.9 * 2 = 12.82nm$

3) Vol  $SiO_2 = .044nm^3$        $25A \rightarrow 2.5nm$   
 $7nm * 14nm * 2.5nm = 245nm^3 = 5568 \text{ molecules}$

4) Resistivity of Aluminum =  $2.8 * 10^{-8} \Omega m$ ,  $R = \frac{\rho * l}{w * t}$   
 $R_{Al} = \frac{(2.8 * 10^{-8}) * (200 * 10^{-6})}{(60 * 10^{-9}) * (60 * 10^{-9})} = 1555.5 \Omega$

5) Silver. Expensive with high electron migration potential.

6) 300mm wafer thickness =  $775 \pm 25 \mu m$ , +150 $\mu m$  for saw = 925 $\mu m$   
 $2m / (925 \pm 25 \mu m) = 2105 \rightarrow 2222$  wafers.

7) What is this.

8a) Length = 1 $\mu m$  Width = 3 $\mu m$

b) Photoresist under-exposed  $\rightarrow$  length = .8 $\mu m$

A combination of both issues leaves width unchanged = 3 $\mu m$ .

c) Width still unchanged, but now issues cancel out so length is unchanged so that length = 1 $\mu m$ .

9)  $\rho_{Al} = 2.8 * 10^{-8} \Omega m$ ,  $R = \frac{\rho * l}{w * t}$   
 $t = \frac{(2.8 * 10^{-8}) * (250 * 10^{-6})}{(2 * 10^{-6}) * 25} = .14 \mu m$

Sheet Resistance =  $\frac{\rho}{t} = \frac{2.8 * 10^{-8}}{.14 * 10^{-6}} = .2 \Omega$

10)  $\rho_{Cu} 1.68 * 10^{-8} \Omega m$ ,  $R = \frac{\rho * l}{w * t}$   
 $l = \frac{(2 * 10^{-6}) * (.14 * 10^{-6}) * 25}{(1.68 * 10^{-8})} = 417 \mu m$

11) Thermal silicon growth uses silicon from substrate, approx .47x full height of oxide. Therefore, if oxide is 5000 $\text{\AA}$ ,  $W_{height}$  increase is  $5000 * (1 - .47) = 2650 \text{\AA}$

12) Sheet resistance given,  $R_{poly} = 23.2 \Omega / sq$  *some things* (thanks for leaving that blank btw, very helpful), and  $R_{p+} = 106.7 \Omega / sq$  *some things*.

As the units are conveniently obfuscated, I will be assuming they are *sq um*.

5k resistor: Poly  $\rightarrow 5000 / 23.2 = 215.52 \mu m$  len,

P+  $\rightarrow 5000 / 106.7 = 46.86 \mu m$  len.

Min size Poly = .2 $\mu m$  x .2 $\mu m$ , Min size P+ = .3 $\mu m$  x .3 $\mu m$

Min Poly serpentine =  $.2 * .2 * 215.52 = 8.62 \mu m^3$ .

Min P+ serpentine =  $.3 * .3 * 46.86 = 4.22 \mu m^3$ .

$8.62 / 4.22 \rightarrow 2.04x$  area increase if using Poly.